Tim Batten

List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/3949479/publications.pdf

Version: 2024-02-01

		1307594	1199594	
13	327	7	12	
papers	citations	h-index	g-index	
13	13	13	886	
all docs	docs citations	times ranked	citing authors	

#	Article	IF	CITATIONS
1	Non-destructive imaging of residual strains in GaN and their effect on optical and electrical properties using correlative light–electron microscopy. Journal of Applied Physics, 2022, 131, 075303.	2.5	1
2	Nanoscale Spatial Resolution in Far-Field Raman Imaging Using Hyperspectral Unmixing in Combination with Positivity Constrained Super-Resolution. Applied Spectroscopy, 2020, 74, 780-790.	2.2	4
3	Thick, Adherent Diamond Films on AlN with Low Thermal Barrier Resistance. ACS Applied Materials & amp; Interfaces, 2019, 11, 40826-40834.	8.0	45
4	Sub-Micron Spatial Resolution in Far-Field Raman Imaging Using Positivity-Constrained Super-Resolution. Applied Spectroscopy, 2019, 73, 902-909.	2.2	6
5	Coaxial nanowires as plasmon-mediated remote nanosensors. Nanoscale, 2018, 10, 6437-6444.	5.6	9
6	Optical characterization of magnesium incorporation in p-GaN layers for core–shell nanorod light-emitting diodes. Journal Physics D: Applied Physics, 2018, 51, 155103.	2.8	11
7	Decoupling of epitaxial graphene via gold intercalation probed by dispersive Raman spectroscopy. Journal of Applied Physics, 2015, 117, 183103.	2.5	3
8	Controlling the Orientation, Edge Geometry, and Thickness of Chemical Vapor Deposition Graphene. ACS Nano, 2013, 7, 1351-1359.	14.6	182
9	Reliability Assessment of a New Power Electronics Packaging Material: Silver Diamond Composite. Journal of Microelectronics and Electronic Packaging, 2013, 10, 54-58.	0.7	1
10	Improved thermal management for GaN power electronics: Silver diamond composite packages. Microelectronics Reliability, 2012, 52, 3022-3025.	1.7	18
11	Substrate-directed formation of calcium carbonate fibres. Journal of Materials Chemistry, 2009, 19, 387-398.	6.7	31
12	Single-crystalline B12As2 on m-plane (11Â⁻00)â€^15R-SiC. Applied Physics Letters, 2008, 92, .	3.3	13
13	Characterising Strain/Stress and Defects in SiC Wafers Using Raman Imaging. Materials Science Forum, 0, 821-823, 229-232.	0.3	3